



Material Content Data Sheet



Sales Product Name				IPP100N10S3-05		Issued		4. July 2019	
MA#				MA003664466					
Package				PG-TO220-3-1		Weight*		2043.05 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	15.369	0.75	0.75	7523	7523	
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120		
	non noble metal	iron	7439-89-6	0.816	0.04		400		
	non noble metal	copper	7440-50-8	815.335	39.90	39.95	399077	399597	
	non noble metal	aluminium	7429-90-5	9.738	0.48	0.48	4766	4766	
wire	non noble metal	aluminium	7429-90-5	9.738	0.48	0.48	4766	4766	
encapsulation	organic material	carbon black	1333-86-4	8.703	0.43		4260		
	plastics	epoxy resin	-	95.734	4.69		46858		
	inorganic material	silicondioxide	60676-86-0	475.767	23.29	28.41	232872	283990	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10505	10505	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	119	120	
solder	non noble metal	tin	7440-31-5	0.188	0.01		92		
	noble metal	silver	7440-22-4	0.235	0.01		115		
	non noble metal	lead	7439-92-1	8.975	0.44	0.46	4393	4600	
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87		
	non noble metal	iron	7439-89-6	0.590	0.03		289		
	non noble metal	copper	7440-50-8	589.466	28.85	28.89	288523	288899	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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